Notice for TAIYO YUDEN products

Please read this notice before using the TAIYO YUDEN products.

!\ REMINDERS

Product information in this catalog is as of October 2016. All of the contents specified herein are subject to change without notice due to technical improvements, etc. Therefore, please check for the latest information carefully before practical application or use of our products.

Please note that TAIYO YUDEN shall not be in any way responsible for any damages and defects in products or equipment incorporating our products, which are caused under the conditions other than those specified in this catalog or individual specification.

- Please contact TAIYO YUDEN for further details of product specifications as the individual specification is available.
- Please conduct validation and verification of our products in actual condition of mounting and operating environment before using our products.
- The products listed in this catalog are intended for use in general electronic equipment (e.g., AV equipment, OA equipment, home electric appliances, office equipment, information and communication equipment), general medical equipment, industrial equipment, and automotive interior applications, etc. Please be sure to contact TAIYO YUDEN for further information before using the products for any equipment which may directly cause loss of human life or bodily injury (e.g., specially controlled medical equipment, transportation equipment including, without limitation, automotive powertrain control system, train control system, and ship control system, traffic signal equipment).

Please do not incorporate our products into any equipment requiring high levels of safety and/or reliability (e.g., aerospace equipment, aviation equipment, nuclear control equipment, undersea equipment, military equipment).

When our products are used even for high safety and/or reliability-required devices or circuits of general electronic equipment, it is strongly recommended to perform a thorough safety evaluation prior to use of our products and to install a protection circuit as necessary.

Please note that unless you obtain prior written consent of TAIYO YUDEN, TAIYO YUDEN shall not be in any way responsible for any damages incurred by you or third parties arising from use of the products listed in this catalog for any equipment requiring inquiry to TAIYO YUDEN or prohibited for use by TAIYO YUDEN as described above.

- Please note that TAIYO YUDEN shall have no responsibility for any controversies or disputes that may occur in connection with a third party's intellectual property rights and other related rights arising from use of our products. TAIYO YUDEN grants no license for such rights.
- Please note that unless otherwise agreed in writing, the scope of warranty for our products is limited to the delivered our products themselves and TAIYO YUDEN shall not be in any way responsible for any damages resulting from a fault or defect in our products.
- The contents of this catalog are applicable to our products which are purchased from our sales offices or authorized distributors (hereinafter "TAIYO YUDEN's official sales channel"). Please note that the contents of this catalog are not applicable to our products purchased from any seller other than TAIYO YUDEN's official sales channel.
- Caution for Export

Some of our products listed in this catalog may require specific procedures for export according to "U.S. Export Administration Regulations", "Foreign Exchange and Foreign Trade Control Law" of Japan, and other applicable regulations. Should you have any questions on this matter, please contact our sales staff.

MULTILAYER CERAMIC CAPACITORS





■PART NUMBER

J	М	Κ	3	1	6	Δ	В	J	1	0	6	М	L	Н	Т	Δ
1	2	3		4		(5)	(3		7		8	9	10	11	12

△=Blank space

End termination

Plated

Soft Termination

Cu Internal Electrodes

High Reliability Application

(J	ا(را	R	a	ted	vo	ľ	ta	g	

2Series name

Code	Rated voltage[VDC]
Α	4
J	6.3
L	10
Е	16
Т	25
G	35
U	50
Н	100
Q	250
S	630

S R

432

3End termination Code

Κ

J

4Dimension(L×	: W)	
Туре	Dimensions (L×W)[mm]	EIA(inch)
063	0.6 × 0.3	0201
105	1.0 × 0.5	0402
105	0.52 × 1.0 💥	0204
107	1.6 × 0.8	0603
107	0.8 × 1.6 💥	0306
212	2.0 × 1.25	0805
212	1.25 × 2.0 💥	0508
316	3.2 × 1.6	1206
325	3.2 × 2.5	1210

4.5 × 3.2

Code Series name

M Multilayer ceramic capacitor

V Multilayer ceramic capacitor for high frequency

W LW reverse type multilayer capacitor

Note: ※LW reverse type(□WK) only

⑤Dimension tolerance

Code	Туре	L[mm]	W[mm]	T[mm]
Δ	ALL	Standard	Standard	Standard
	063	0.6±0.05	0.3±0.05	0.3±0.05
	105	1.0±0.10	0.5±0.10	0.5±0.10
	107	1.6+0.15/-0.05	0.8+0.15/-0.05	0.8+0.15/-0.05
Α	010	0.0 1.0 15 / 0.05	105 1015/ 005	0.85±0.10
	212	2.0 + 0.15 / -0.05	1.25 + 0.15 / -0.05	1.25+0.15/-0.05
	316	3.2±0.20	1.6±0.20	1.6±0.20
	325	3.2±0.30	2.5±0.30	2.5±0.30
	105	1.0+0.15/-0.05	0.5+0.15/-0.05	0.5+0.15/-0.05
	107	1.6+0.20/-0	0.8+0.20/-0	0.8+0.20/-0
В	212	2.0+0.20/-0	1.25+0.20/-0	0.85±0.10
	212	2.0+0.20/ -0	1.25+0.20/ -0	1.25+0.20/-0
	316	3.2±0.30	1.6±0.30	1.6±0.30
	105	1.0+0.20/-0	0.5+0.20/-0	0.5+0.20/-0
С	107	1.6+0.25/-0	0.8 + 0.25 / -0	0.8 + 0.25 / -0
	212	2.0+0.25/-0	1.25+0.25/-0	1.25 + 0.25 / -0
	212	2.0±0.15	1.25±0.15	0.85±0.15
K	316	3.2±0.20	1.6±0.20	1.15±0.20
K	310	3.2 ± 0.20	1.0 ± 0.20	1.6±0.20
	325	3.2±0.50	2.5±0.30	2.5 ± 0.30

Note: P. 22 Standard external dimensions

Δ= Blank space

1812

©Temperature characteristics code

■High dielectric type

Code	Applicable standard				Temperature range[°C]	Ref. Temp.[°C]	Capacitance change	Capacitance tolerance	Tolerance code										
	ΕIΛ	X5R	−55 ~ + 85	25	±15%	±10%	K												
	BJ EIA X		-55°° + 65	20	上15%	±20%	М												
C6	00 FIA V		-55 ~ +105	25	±22%	±10%	K												
	C6 EIA	X6S	-55~+105	25	± 22 70	±20%	М												
В7	EIA	EIA V7D	VZD	VZD	VZD	V7D	CIA V7D	CIA V7D	-1A V7D	V2D	EIA V7D	ETA V7D	ETA V7D	EIA X7R	-55 ~ +125	25	±15%	±10%	K
Б/	B/ EIA ^/		-55.4 + 125	25	±1370	±20%	М												
C7	EIA	X7S	-55 ~ +125	25	±22%	±10%	K												
	LIA	A/3	-55° + 125	20	1 22 70	±20%	М												
D7	EIA X	A V7T	-55 ~ +125	25	+22%/-33%	±10%	K												
		^/1	_55.3 + 125		+2270/ - 33%	±20%	М												

[▶] This catalog contains the typical specification only due to the limitation of space. When you consider the purchase of our products, please check our specification. For details of each product (characteristics graph, reliability information, precautions for use, and so on), see our website (http://www.ty-top.com/) .

■Temperature compensating type

<u></u>	Tomporacare compensating type									
Code		cable idard	Temperature range[°C]	Ref. Temp.[°C]	Capacitance change	Capacitance tolerance	Tolerance code			
						±0.1pF	В			
	JIS	CG		20		±0.25pF	С			
CG			-55 ~ +125		0±30ppm/°C	±0.5pF	D			
CG						-55.4 + 125		о±зоррпі/ С	±1pF	F
	EIA	EIA COG	COG	25		±2%	G			
						±5%	J			

7Nominal capacitance

(Fitominal capacitance						
Code (example)	Nominal cpacitance					
0R5	0.5pF					
010	1pF					
100	10pF					
101	100pF					
102	1,000pF					
103	0.01 <i>μ</i> F					
104	0.1 μ F					
105	1.0 <i>μ</i> F					
106	10 μ F					
107	100 μ F					

Note : R=Decimal point

8 Capacitance tolerance

Code	Capacitance tolerance
В	±0.1pF
С	±0.25pF
D	±0.5pF
G	±2%
J	±5%
K	±10%
М	±20%

Thickness

Code	Thickness[mm]
Р	0.3
Т	0.3
V	0.5
С	0.7(107type or more)
Α	0.8
D	0.85(212type or more)
F	1.15
G	1.25
Н	1.5
L	1.6
N	1.9
М	2.5

10Special code

Code	Special code
Н	MLCC for Industrial and Automotive

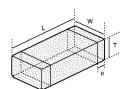
①Packaging

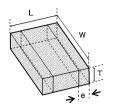
Code	Packaging
F	ϕ 178mm Taping (2mm pitch)
R	ϕ 178mm Embossed Taping (4mm pitch)
Т	ϕ 178mm Taping (4mm pitch)
	ϕ 178mm Taping (4mm pitch, 1000 pcs/reel)
P	325 type(Thickness code M)

①Internal code

9	
Code	Internal code
Δ	Standard

[▶] This catalog contains the typical specification only due to the limitation of space. When you consider the purchase of our products, please check our specification. For details of each product (characteristics graph, reliability information, precautions for use, and so on), see our website (http://www.ty-top.com/).





 \divideontimes LW reverse type

Tuno(FIA)		Dime	nsion [mm] (inch)			
Type(EIA)	L	W	T	*1	е	
DM/(000/0001)	0.6±0.03	0.3±0.03	0.3±0.03	_	0.15±0.05	
□MK063(0201)	(0.024 ± 0.001)	(0.012 ± 0.001)	(0.012 ± 0.001)	Т	(0.006 ± 0.002)	
DMK10E (0400)	1.0±0.05	0.5±0.05	0.5±0.05	٧	0.25±0.10	
□MK105(0402)	(0.039 ± 0.002)	(0.020 ± 0.002)	(0.020 ± 0.002)	V	(0.010 ± 0.004)	
TWIC10E (0004) \	0.52±0.05	1.0±0.05	0.3±0.05	Р	0.18±0.08	
⊐WK105(0204)※	(0.020 ± 0.002)	(0.039 ± 0.002)	(0.012 ± 0.002)	Р	(0.007 ± 0.003)	
TMK107(0000)	1.6±0.10	0.8±0.10	0.8±0.10		0.35±0.25	
□MK107(0603)	(0.063 ± 0.004)	(0.031 ± 0.004)	(0.031 ± 0.004)	Α	(0.014 ± 0.010)	
TM 1407 (0000)	1.6±0.10	0.8±0.10	0.8±0.10		0.35+0.3/-0.25	
⊐MJ107(0603)	(0.063 ± 0.004)	(0.031 ± 0.004)	(0.031 ± 0.004)	Α	(0.014 + 0.012 / -0.010)	
TVC107(0000)	1.6±0.10	0.8±0.10	0.7±0.10	_	0.35±0.25	
□VS107(0603)	(0.063 ± 0.004)	(0.031 ± 0.004)	(0.028 ± 0.004)	С	(0.014 ± 0.010)	
TMD407(0000)	1.6±0.10	0.8±0.10	0.8±0.10	•	0.1~0.6	
⊐MR107(0603)	(0.063 ± 0.004)	(0.031 ± 0.004)	(0.031 ± 0.004)	Α	(0.004~0.024)	
	0.8±0.10	1.6±0.10	0.5±0.05		0.25±0.15	
⊐WK107(0306)※	(0.031 ± 0.004)	(0.063 ± 0.004)	(0.020 ± 0.002)	V	(0.010 ± 0.006)	
	((0.85±0.10		(33232227	
	2.0±0.10	1.25±0.10	(0.033±0.004)	D	0.5±0.25	
□MK212(0805)	(0.079±0.004)	(0.049 ± 0.004)	1.25±0.10	 	(0.020±0.010)	
	(0.073 ± 0.004)	(0.043 ± 0.004)	(0.049±0.004)	G	(0.020±0.010)	
	 		0.049±0.004)	 		
	001010	405.0.0		D	051055/ 055	
□MJ212(0805)	2.0±0.10	1.25±0.10	(0.033±0.004)		0.5+0.35/-0.25	
	(0.079 ± 0.004)	(0.049 ± 0.004)	1.25±0.10	G	(0.020 + 0.014 / -0.010)	
			(0.049 ± 0.004)			
□VS212(0805)	2.0±0.10	1.25±0.10	0.85±0.10	D	0.5±0.25	
1 40212 (0000)	(0.079 ± 0.004)	(0.049 ± 0.004)	(0.033 ± 0.004)		(0.020 ± 0.010)	
□MR212(0805)	2.0 ± 0.10	1.25±0.10	1.25±0.10	G	0.25~0.75	
JIVIN212 (0003)	(0.079 ± 0.004)	(0.049 ± 0.004)	(0.049 ± 0.004)	G	(0.010~0.029)	
JWK010 (0E00) %	1.25±0.15	2.0±0.15	0.85±0.10	7	0.3±0.2	
⊒WK212(0508)※	(0.049 ± 0.006)	(0.079 ± 0.006)	(0.033 ± 0.004)	D	(0.012 ± 0.008)	
			1.15±0.10	_		
	3.2±0.15	1.6±0.15	(0.045 ± 0.004)	F	0.5+0.35/-0.25	
∃MK316(1206)	(0.126±0.006)	(0.063±0.006)	1.6±0.20		(0.020+0.014/-0.010)	
	(0.120 ± 0.000)	(0.000 ± 0.000)		L	(0.020+0.014/-0.01	
			(0.063±0.008)			
			1.15±0.10	F		
□MJ316(1206)	3.2±0.15	1.6±0.15	(0.045 ± 0.004)	'	0.6 + 0.4 / -0.3	
1110310(1200)	(0.126 ± 0.006)	(0.063 ± 0.006)	1.6±0.20		(0.024+0.016/-0.012)	
			(0.063 ± 0.008)	L		
TMD040(4000)	3.2±0.15	1.6±0.15	1.6±0.20		0.25~0.85	
∃MR316(1206)	(0.126±0.006)	(0.063 ± 0.006)	(0.063 ± 0.008)	L	(0.010~0.033)	
			1.15±0.10	_		
			(0.045 ± 0.004)	F		
			1.5±0.10	 	1	
	3.2±0.30	2.5±0.20	(0.059 ± 0.004)	Н	0.6±0.3	
∃MK325(1210)	(0.126±0.012)	(0.098±0.008)	1.9±0.20	 	(0.024±0.012)	
	(323.20.012)	(0.000 ± 0.000)	(0.075±0.008)	N	(5.52 1 2 5.512)	
			2.5±0.20		+	
			(0.098±0.008)	M		
	 			 		
	001000	0.5 / 0.00	1.9±0.20	N	00104/ 05	
]MJ325(1210)	3.2±0.30	2.5±0.20	(0.075±0.008)	-	0.6+0.4/-0.3	
	(0.126±0.012)	(0.098 ± 0.008)	2.5±0.20	М	(0.024+0.016/-0.012	
			(0.098 ± 0.008)			
			1.9±0.20	N		
	3.2±0.30	2.5±0.20	(0.075 ± 0.008)		0.3~0.9	
TMR325 (1210)	5(1210) (0.126±0.012)	(0.098 ± 0.008)	2.5±0.20		(0.012~0.035)	
□MR325(1210)	(0.126±0.012)	(0.030 ± 0.000)		1 1/4		
□MR325(1210)	(0.126±0.012)	(0.030 ± 0.000)	(0.098±0.008)	М		
□MR325(1210) □MK432(1812)	(0.126±0.012) 4.5±0.40	3.2±0.30	(0.098±0.008) 2.5±0.20	M M	0.9±0.6	

Note: X. LW reverse type, *1.Thickness code

[▶] This catalog contains the typical specification only due to the limitation of space. When you consider the purchase of our products, please check our specification. For details of each product (characteristics graph, reliability information, precautions for use, and so on), see our website (http://www.ty-top.com/) .

STANDARD QUANTITY

т	EIA (inch)	Dime	nsion	Standard qu	uantity[pcs]
Type	EIA (inch)	[mm]	Code	Paper tape	Embossed tape
063	0201	0.3	Т	15000	_
105	0402	0.5	V	10000	
105	0204 ※	0.30	Р	10000	_
		0.7	С	4000	
		0.8	Α	4000	_
107	0603	0.8	А	3000 (Soft Termination)	_
		0.8	А	_	3000 (Soft Termination)
	0306 ※	0.50	V	_	4000
		0.85	D	4000	_
	0805	1.25	G	_	3000
212	0805	1.25	G	_	2000 (Soft Termination
	0508 ※	0.85	D	4000	-
010	1000	1.15	F	_	3000
316	1206	1.6	L	_	2000
		1.15	F		
205	1010	1.5	Н	_	2000
325	1210	1.9	N		
		2.5	М	_	500(T), 1000(P)
432	1812	2.5	М	-	500

Note : ※.LW Reverse type(□WK)

[▶] This catalog contains the typical specification only due to the limitation of space. When you consider the purchase of our products, please check our specification. For details of each product (characteristics graph, reliability information, precautions for use, and so on), see our website (http://www.ty-top.com/).

Soft Termination Multilayer Ceramic Capacitors

●107TYPE (Dimension:1.6 × 0.8mm JIS:1608 EIA:0603)

[Temperature Characteristic B7 : X7R] 0.8mm thickness(A)

Part number 1	Part number 2	Rated voltage [V]	Temperature characteristics	Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT Rated voltage x %	Thickness*3 [mm]	Note
TMJ107BB7473[]AHT			X7R	0.047 μ	±10, ±20	3.5	200	0.8+0.20/-0	*1 ,*2
TMJ107BB7104[]AHT			X7R	0.1 μ	±10, ±20	3.5	200	0.8+0.20/-0	*1 ,*2
TMJ107BB7224[]AHT		25	X7R	0.22 μ	±10, ±20	10	150	0.8+0.20/-0	*1 ,*2
TMJ107BB7474[]AHT			X7R	0.47 μ	±10, ±20	10	150	0.8+0.20/-0	*1 ,*2
TMJ107CB7105[AHR			X7R	1 μ	±10, ±20	10	150	0.8+0.25/-0	*1 ,*2
GMJ107BB7473[]AHT			X7R	0.047 μ	±10, ±20	3.5	200	0.8+0.20/-0	*1 ,*2
GMJ107BB7104[]AHT			X7R	0.1 μ	±10, ±20	3.5	200	0.8+0.20/-0	*1 ,*2
GMJ107BB7224□AHT		35	X7R	0.22 μ	±10, ±20	10	150	0.8+0.20/-0	*1 ,*2
GMJ107BB7474[]AHT			X7R	0.47 μ	±10, ±20	10	150	0.8+0.20/-0	*1 ,*2
GMJ107CB7105∏AHR			X7R	1 μ	±10, ±20	10	150	0.8+0.25/-0	*1 ,*2
UMJ107AB7102∏AHT			X7R	1000 p	±10, ±20	3.5	200	0.8+0.15/-0.05	*1 ,*2
UMJ107AB7222 AHT			X7R	2200 p	±10, ±20	3.5	200	0.8+0.15/-0.05	*1 ,*2
UMJ107BB7472 AHT			X7R	4700 p	±10, ±20	3.5	200	0.8+0.20/-0	*1 ,*2
UMJ107BB7103∏AHT		50	X7R	0.01 μ	±10, ±20	3.5	200	0.8+0.20/-0	*1 ,*2
UMJ107BB7223∏AHT			X7R	0.022 μ	±10, ±20	3.5	200	0.8+0.20/-0	*1 ,*2
UMJ107BB7473∏AHT			X7R	0.047 μ	±10, ±20	3.5	200	0.8+0.20/-0	*1 ,*2
UMJ107BB7104∏AHT			X7R	0.1 μ	±10, ±20	3.5	200	0.8+0.20/-0	*1 ,*2
HMJ107AB7102□AHT			X7R	1000 p	±10, ±20	3.5	200	0.8+0.15/-0.05	*1 ,*2
HMJ107AB7222□AHT			X7R	2200 p	±10, ±20	3.5	200	0.8+0.15/-0.05	*1 ,*2
HMJ107BB7472∏AHT			X7R	4700 p	±10, ±20	3.5	200	0.8+0.20/-0	*1 ,*2
HMJ107BB7103∏AHT		100	X7R	0.01 μ	±10, ±20	3.5	200	0.8+0.20/-0	*1 ,*2
HMJ107BB7223∏AHT			X7R	0.022 μ	±10, ±20	3.5	200	0.8+0.20/-0	*1 ,*2
HMJ107BB7473∏AHT			X7R	0.047 μ	±10, ±20	3.5	200	0.8+0.20/-0	*1 ,*2
HMJ107BB7104 AHT			X7R	0.1 μ	±10, ±20	3.5	200	0.8+0.20/-0	*1 ,*2

212TYPE (Dimension:2.0 × 1.25mm JIS:2012 EIA:0805)

Temperature Characterist			Ta man a washi wa	Capacitance	Capacitance	tan δ	HTLT		
Part number 1	Part number 2	Rated voltage [V]	characteristics	[F]	tolerance [%]	[%]	Rated voltage x %	Thickness*3 [mm]	Note
JMJ212CB7106∏GHT		6.3	X7R	10 μ	±10, ±20	10	150	1.25+0.25/-0	*1 ,*2
EMJ212CB7225 GHT		16	X7R	2.2 μ	±10, ±20	10	150	1.25+0.25/-0	*1 ,*2
EMJ212CB7475 GHT		10	X7R	4.7 μ	±10, ±20	10	150	1.25+0.25/-0	*1 ,*2
TMJ212CB7225[]GHT		25	X7R	2.2 μ	±10, ±20	10	150	1.25+0.25/-0	*1 ,*2
GMJ212CB7105 GHT		35	X7R	1 μ	±10, ±20	10	150	1.25+0.25/-0	*1 ,*2
UMJ212BB7103[]GHT			X7R	0.01 μ	±10, ±20	2.5	200	1.25+0.20/-0	*1 ,*2
UMJ212BB7223[]GHT			X7R	0.022 μ	±10, ±20	2.5	200	1.25+0.20/-0	*1 ,*2
UMJ212BB7473[]GHT		50	X7R	0.047 μ	±10, ±20	3.5	200	1.25+0.20/-0	*1 ,*2
UMJ212BB7104[]GHT			X7R	0.1 μ	±10, ±20	3.5	200	1.25+0.20/-0	*1 ,*2
UMJ212CB7105[]GHT			X7R	1 μ	±10, ±20	10	150	1.25+0.25/-0	*1 ,*2
HMJ212KB7102 DHT			X7R	1000 p	±10, ±20	2.5	200	0.85±0.15	*1 ,*2
HMJ212KB7222[]DHT			X7R	2200 p	±10, ±20	2.5	200	0.85 ± 0.15	*1 ,*2
HMJ212BB7472[]GHT			X7R	4700 p	±10, ±20	2.5	200	1.25+0.20/-0	*1 ,*2
HMJ212BB7103[]GHT		100	X7R	0.01 μ	±10, ±20	2.5	200	1.25+0.20/-0	*1 ,*2
HMJ212BB7223[]GHT		100	X7R	0.022 μ	±10, ±20	3.5	200	1.25+0.20/-0	*1 ,*2
HMJ212BB7473[]GHT			X7R	0.047 μ	±10, ±20	3.5	200	1.25+0.20/-0	*1 ,*2
HMJ212BB7104 GHT			X7R	0.1 μ	±10, ±20	3.5	200	1.25+0.20/-0	*1 ,*2
HMJ212BB7224[]GHT			X7R	0.22 μ	±10, ±20	3.5	200	1.25+0.20/-0	*1 ,*2
QMJ212KB7102DHT			X7R	1000 p	±10, ±20	2.5	150	0.85±0.15	*1 ,*2
QMJ212KB7222 DHT			X7R	2200 p	±10, ±20	2.5	150	0.85±0.15	*1 ,*2
QMJ212BB7472[]GHT		250	X7R	4700 p	±10, ±20	2.5	150	1.25+0.20/-0	*1 ,*2
QMJ212BB7103[]GHT			X7R	0.01 μ	±10, ±20	2.5	150	1.25+0.20/-0	*1 ,*2
QMJ212BB7223[]GHT			X7R	0.022 μ	±10, ±20	2.5	150	1.25+0.20/-0	*1 ,*2

●316TYPE (Dimension:3.2 × 1.6mm JIS:3216 EIA:1206)

Temperature Characterist	Temperature Characteristic B7 : X7R 1.15mm thickness(F), 1.6mm thickness(L)											
Deat words of	Dt	D . I II D4	Temperature	Capacitance	Capacitance	tan δ	HTLT	*3 - 3	N			
Part number 1	Part number 2	Rated voltage [V]	characteristics	[F]	tolerance [%]	[%]	Rated voltage x %	Thickness*3 [mm]	Note			
LMJ316BB7226[]LHT		10	X7R	22 μ	±10, ±20	10	150	1.6±0.30	*1 ,*2			
EMJ316BB7475 LHT		16	X7R	4.7 μ	±10, ±20	10	150	1.6±0.30	*1 ,*2			
EMJ316BB7106[]LHT		10	X7R	10 μ	±10, ±20	10	150	1.6±0.30	*1 ,*2			
TMJ316BB7474 LHT			X7R	0.47 μ	±10, ±20	3.5	200	1.6±0.30	*1 ,*2			
TMJ316BB7475 LHT		25	X7R	4.7 μ	±10, ±20	10	150	1.6±0.30	*1 ,*2			
TMJ316BB7106□LHT			X7R	10 μ	±10, ±20	10	150	1.6±0.30	*1 ,*2			
GMJ316BB7474[LHT			X7R	0.47 μ	±10, ±20	3.5	200	1.6±0.30	*1 ,*2			
GMJ316AB7225[]LHT		35	X7R	2.2 μ	±10, ±20	10	150	1.6±0.20	*1 ,*2			
GMJ316BB7475[]LHT		30	X7R	4.7 μ	±10, ±20	10	150	1.6±0.30	*1 ,*2			
GMJ316BB7106 LHT			X7R	10 μ	±10, ±20	10	150	1.6±0.30	*1 ,*2			
UMJ316BB7473 LHT			X7R	0.047 μ	±10, ±20	2.5	200	1.6±0.30	*1 ,*2			
UMJ316BB7104□LHT			X7R	0.1 μ	±10, ±20	3.5	200	1.6±0.30	*1 ,*2			
UMJ316BB7224 LHT		50	X7R	0.22 μ	±10, ±20	3.5	200	1.6±0.30	*1 ,*2			
UMJ316BB7474 LHT		30	X7R	0.47 μ	±10, ±20	3.5	200	1.6±0.30	*1 ,*2			
UMJ316BB7105□LHT			X7R	1 μ	±10, ±20	3.5	200	1.6±0.30	*1 ,*2			
UMJ316AB7225□LHT			X7R	2.2 μ	±10, ±20	10	150	1.6±0.20	*1 ,*2			
HMJ316 B7102∏FHT			X7R	1000 p	±10, ±20	2.5	200	1.15±0.10	*1 ,*2			
HMJ316 B7222∏FHT			X7R	2200 p	±10, ±20	2.5	200	1.15±0.10	*1 ,*2			
HMJ316 B7472∏FHT			X7R	4700 p	±10, ±20	2.5	200	1.15±0.10	*1 ,*2			
HMJ316KB7103∏FHT			X7R	0.01 μ	±10, ±20	2.5	200	1.15±0.20	*1 ,*2			
HMJ316BB7223□LHT		100	X7R	0.022 μ	±10, ±20	2.5	200	1.6±0.30	*1 ,*2			
HMJ316BB7473□LHT		100	X7R	0.047 μ	±10, ±20	2.5	200	1.6±0.30	*1 ,*2			
HMJ316BB7104□LHT]	X7R	0.1 μ	±10, ±20	2.5	200	1.6±0.30	*1 ,*2			
HMJ316BB7224□LHT		1	X7R	0.22 μ	±10, ±20	3.5	200	1.6±0.30	*1 ,*2			
HMJ316BB7474□LHT]	X7R	0.47 μ	±10, ±20	3.5	200	1.6±0.30	*1 ,*2			
HMJ316BB7105[]LHT			X7R	1 μ	±10, ±20	3.5	200	1.6±0.30	*1 ,*2			

[▶] This catalog contains the typical specification only due to the limitation of space. When you consider the purchase of our products, please check our specification. For details of each product (characteristics graph, reliability information, precautions for use, and so on), see our website (http://www.ty-top.com/) .

Part number 1	Part number 2	Rated voltage [V]	Tempe	erature	Capacitance	Capacitance	tan δ	HTLT	Thickness*3 [mm]	Note
Part number 1	Part number 2	Rated voitage [v]	charact	characteristics [F]		tolerance [%]	[%]	Rated voltage x %	Inickness [mm]	Note
QMJ316 B7102[]FHT				X7R	1000 p	±10, ±20	2.5	150	1.15±0.10	*1 ,*2
QMJ316 B7222[]FHT				X7R	2200 p	±10, ±20	2.5	150	1.15±0.10	*1 ,*2
QMJ316 B7472[]FHT				X7R	4700 p	±10, ±20	2.5	150	1.15±0.10	*1 ,*2
QMJ316KB7103[]FHT		250		X7R	0.01 μ	±10, ±20	2.5	150	1.15±0.20	*1 ,*2
QMJ316BB7223[]LHT				X7R	0.022 μ	±10, ±20	2.5	150	1.6±0.30	*1 ,*2
QMJ316BB7473[]LHT				X7R	0.047 μ	±10, ±20	2.5	150	1.6±0.30	*1 ,*2
QMJ316BB7104[]LHT				X7R	0.1 μ	±10, ±20	2.5	150	1.6±0.30	*1 ,*2
SMJ316 B7102□FHT				X7R	1000 p	±10, ±20	2.5	120	1.15±0.10	*1 ,*2
SMJ316 B7222 FHT				X7R	2200 p	±10, ±20	2.5	120	1.15±0.10	*1 ,*2
SMJ316 B7472□FHT		630		X7R	4700 p	±10, ±20	2.5	120	1.15±0.10	*1 ,*2
SMJ316KB7103[FHT				X7R	0.01 μ	±10, ±20	2.5	120	1.15±0.20	*1 ,*2
SMJ316BB7223 LHT				X7R	0.022 μ	±10, ±20	2.5	120	1.6±0.30	*1 ,*2

325TYPE (Dimension:3.2 × 2.5mm JIS:3225 EIA:1210)

[Temperature Characteristic B7 : X7R] 1.9mm thickness(N), 2.5mm thickness(M)

Part number 1	Part number 2	Rated voltage [V]	Temperature	Capacitance	Capacitance	tan δ	HTLT	Thickness*3 [mm]	Note
T art number 1	Tarc Humber 2	Nated Voltage [V]	characteristics	[F]	tolerance [%]	[%]	Rated voltage x %	Thickness [mm]	14006
JMJ325KB7476∏MHP	JMJ325KB7476[]MHT	6.3	X7R	47 μ	±10, ±20	10	150	2.5±0.30	*1 ,*2
EMJ325KB7226□MHP	EMJ325KB7226 MHT	16	X7R	22 μ	±10, ±20	10	150	2.5±0.30	*1 ,*2
TMJ325AB7475 MHP	TMJ325AB7475[MHT	25	X7R	4.7 μ	±10, ±20	2.5	150	2.5±0.30	*1 ,*2
TMJ325KB7106□MHP	TMJ325KB7106☐MHT	20	X7R	10 μ	±10, ±20	10	150	2.5±0.30	*1 ,*2
GMJ325AB7475[MHP	GMJ325AB7475[MHT	35	X7R	4.7 μ	±10, ±20	2.5	150	2.5±0.30	*1 ,*2
GMJ325KB7106 MHP	GMJ325KB7106□MHT	00	X7R	10 μ	±10, ±20	10	150	2.5±0.30	*1 ,*2
UMJ325AB7225[MHP	UMJ325AB7225[MHT		X7R	2.2 μ	±10, ±20	3.5	200	2.5±0.30	*1 ,*2
UMJ325AB7475 MHP	UMJ325AB7475[MHT	50	X7R	4.7 μ	±10, ±20	2.5	150	2.5±0.30	*1 ,*2
UMJ325KB7106 MHP	UMJ325KB7106∏MHT		X7R	10 μ	±10, ±20	10	150	2.5±0.30	*1 ,*2
HMJ325 B7223[NHT			X7R	0.022 μ	±10, ±20	2.5	200	1.9±0.20	*1 ,*2
HMJ325 B7473[NHT			X7R	0.047 μ	±10, ±20	2.5	200	1.9±0.20	*1 ,*2
HMJ325 B7104[]NHT			X7R	0.1 μ	±10, ±20	2.5	200	1.9±0.20	*1 ,*2
HMJ325 B7224 NHT		100	X7R	0.22 μ	±10, ±20	2.5	200	1.9±0.20	*1 ,*2
HMJ325 B7474[NHT			X7R	0.47 μ	±10, ±20	3.5	200	1.9±0.20	*1 ,*2
HMJ325 B7105□NHT			X7R	1 μ	±10, ±20	3.5	200	1.9±0.20	*1 ,*2
HMJ325AB7225 MHP	HMJ325AB7225 MHT		X7R	2.2 μ	±10, ±20	3.5	200	2.5±0.30	*1 ,*2
QMJ325 B7223[NHT			X7R	0.022 μ	±10, ±20	2.5	150	1.9±0.20	*1 ,*2
QMJ325 B7473[NHT		250	X7R	0.047 μ	±10, ±20	2.5	150	1.9±0.20	*1 ,*2
QMJ325 B7104[NHT		250	X7R	0.1 μ	±10, ±20	2.5	150	1.9±0.20	*1 ,*2
QMJ325 B7224[NHT			X7R	0.22 μ	±10, ±20	2.5	150	1.9±0.20	*1 ,*2
SMJ325 B7223 NHT		630	X7R	0.022 μ	±10, ±20	2.5	120	1.9±0.20	*1 ,*2
SMJ325 B7473[NHT		030	X7R	0.047 μ	±10, ±20	2.5	120	1.9±0.20	*1 ,*2

LW Reversal Decoupling Capacitors (LWDCTM)

■105TYPE (Dimension:0.52 × 1.0mm JIS:0510 EIA:0204)

[Temperature Characteristic BJ : X5R] 0.3mm thickness(P)

Part number 1	Part number 2	Rated voltage [V]	Tempe	rature	Capacitance	Capacitance	tan δ	HTLT	Thickness*3 [mm]	Note
rart number i	Fart Humber 2	Nated voltage [v]	charact	eristics	[F]	tolerance [%]	[%]	Rated voltage x %	Thickness [mm]	Note
TWK105 BJ104MPHF		25		X5R	0.1 μ	±20	5	150	0.3±0.05	*1 ,*2
EWK105 BJ224MPHF		16		X5R	0.22 μ	±20	10	150	0.3±0.05	*1 ,*2
LWK105 BJ474MPHF		10		X5R	0.47 μ	±20	10	150	0.3±0.05	*1 ,*2
AWK105 BJ105MPHF		4		X5R	1 μ	±20	10	150	0.3±0.05	*1 ,*2

 $\begin{tabular}{c} \textbf{[Temperature Characteristic C6: X6S, C7: X7S]} & 0.3mm thickness(P) \\ \end{tabular}$

Part number 1	Part number 2	Rated voltage [V]	Temperature	Capacitance	Capacitance	tan δ	HTLT	Thickness*3 [mm]	Note
T art Humber 1	1 art number 2	Nated Voltage [V]	characteristics	[F]	tolerance [%]	[%]	Rated voltage x %	Thickness [mm]	14010
EWK105 C6104MPHF		16	X6S	0.1 μ	±20	5	150	0.3±0.05	*1 ,*2
LWK105 C7104MPHF		10	X7S	0.1 μ	±20	5	150	0.3±0.05	*1 ,*2
LWK105 C6224MPHF		10	X6S	0.22 μ	±20	10	150	0.3±0.05	*1 ,*2
JWK105 C7104MPHF			X7S	0.1 μ	±20	5	150	0.3±0.05	*1 ,*2
JWK105 C7224MPHF		6.3	X7S	0.22 μ	±20	10	150	0.3±0.05	*1 ,*2
JWK105 C6474MPHF			X6S	0.47 μ	±20	10	150	0.3±0.05	*1 ,*2
AWK105 C7224MPHF		4	X7S	0.22 μ	±20	10	150	0.3±0.05	*1 ,*2
AWK105 C6474MPHF		4	X6S	0.47 μ	±20	10	150	0.3 ± 0.05	*1 ,*2

●107TYPE (Dimension:0.8 × 1.6mm JIS:0816 EIA:0306)

[Temperature Characteristic BJ : X5R] 0.5mm thickness(V)

Part number 1	Part number 2	Rated voltage [V]	Tempe	erature	Capacitance	Capacitance	$ an\delta$	HTLT	Thickness*3 [mm]	Note
i ai ciidilibei i	T art Humber 2	characteristics [F] toler	tolerance [%]	[%]	Rated voltage x %	Thickness [mm]	Note			
LWK107 BJ105MVHT		10		X5R	1 μ	±20	10	150	0.5±0.05	*1 ,*2
JWK107 BJ225MVHT		6.3		X5R	2.2 μ	±20	10	150	0.5±0.05	*1 ,*2
JWK107 BJ475MVHT		0.3		X5R	4.7 μ	±20	10	150	0.5 ± 0.05	*1 ,*2

 $\begin{tabular}{ll} \textbf{[Temperature Characteristic B7: X7R, C6: X6S, C7: X7S]} & 0.5mm & thickness (V) \\ \end{tabular}$

Part number 1	Part number 2	Rated voltage [V]	Temperature characteristics	Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT Rated voltage x %	Thickness*3 [mm]	Note
TWK107 B7104MVHT		25	X7R	0.1 μ	±20	5	150	0.5±0.05	*1 ,*2
EWK107 B7224MVHT		16	X7R	0.22 μ	±20	5	150	0.5±0.05	*1 ,*2
EWK107 B7474MVHT		10	X7R	0.47 μ	±20	5	150	0.5±0.05	*1 ,*2
LWK107 B7474MVHT		10	X7R	0.47 μ	±20	5	150	0.5±0.05	*1 ,*2
JWK107 C7105MVHT		6.3	X7S	1 μ	±20	10	150	0.5±0.05	*1 ,*2
AWK107 C6225MVHT		4	X6S	2.2 μ	±20	10	150	0.5 ± 0.05	*1 ,*2
AWK107 C6475MVHT]	X6S	4.7 μ	±20	10	150	0.5 ± 0.05	*1 ,*2

[▶] This catalog contains the typical specification only due to the limitation of space. When you consider the purchase of our products, please check our specification. For details of each product (characteristics graph, reliability information, precautions for use, and so on), see our website (http://www.ty-top.com/).

Multilayer Ceramic Capacitors

■PACKAGING

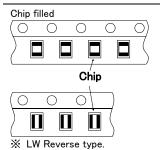
1 Minimum Quantity

Taped package				
Type(EIA)	Thick	ness	Standard o	quantity [pcs]
Type(LIA)	mm	code	Paper tape	Embossed tape
☐MK021(008004)	0.125	K	_	50000
☐MK042(01005)	0.2	C, D	_	40000
□VS042(01005)	0.2	С		40000
☐MK063(0201)	0.3	P,T	15000	_
□WK105(0204) ※	0.3	Р	10000	_
	0.13	Н	_	20000
	0.18	Е	_	15000
☐MK105(0402)	0.2	С	20000	_
	0.3	Р	15000	_
	0.5	V	10000	_
□VK105(0402)	0.5	W	10000	_
□MK107(0603)	0.45	К	4000	_
□WK107(0306) ※	0.5	V	_	4000
□MR107(0603)	0.8	Α	4000	_
□VS107(0603)	0.7	С	4000	_
□MJ107(0603)	0.8	Α	3000	3000
□MK212(0805)	0.45	К	4000	
□WK212(0508) ※	0.85	D	4000	
□MR212(0805)	1.25	G	_	3000
□VS212(0805)	0.85	D	4000	_
ΠΜ (010/000F)	0.85	D	4000	_
□MJ212(0805)	1.25	G	_	2000
51.1 (01.0(1.000)	0.85	D	4000	_
□MK316(1206) □MR316(1206)	1.15	F	_	3000
□INIK310(1200)	1.6	L	_	2000
[] M 104 0/4 000)	1.15	F	_	3000
□MJ316(1206)	1.6	L	_	2000
	0.85	D		
[] M ((((((((((((((((((1.15	F		2000
☐MK325(1210)	1.9	N	_	2000
□MR325(1210)	2.0max.	Υ		
	2.5	М	_	1000
ΠΜ (205/1010)	1.9	N	_	2000
□MJ325(1210)	2.5	М	_	500(T), 1000(P)
□MK432(1812)	2.5	М	_	500

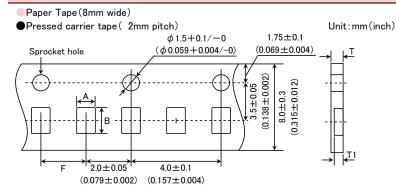
Note: X LW Reverse type.

**No bottom tape for pressed carrier tape Card board carrier tape Top tape Base tape Sprocket hole Chip cavity Base tape Chip cavity

This catalog contains the typical specification only due to the limitation of space. When you consider the purchase of our products, please check our specification. For details of each product (characteristics graph, reliability information, precautions for use, and so on), see our Web site (http://www.ty-top.com/).



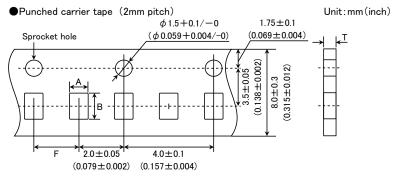
3 Representative taping dimensions



Type(EIA)	Chip Cavity		Insertion Pitch	Tape Thickness	
Type(EIA)	Α	В	F	Т	T1
□MK063(0201)	0.37	0.67		0.45max.	0.42max.
□WK105(0204) ※			20+005	0.45max.	
□MK105(0402) (*1 C)	0.65	1.15	2.0±0.05	0.4max.	0.3max.
□MK105(0402) (*1 P)				0.45max.	0.42max.

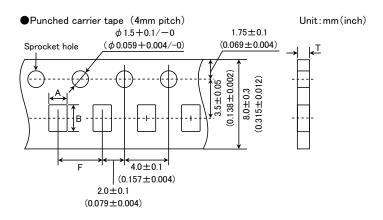
Note *1 Thickness, C:0.2mm ,P:0.3mm. * LW Reverse type.

Unit:mm



Type(EIA)	Chip (Cavity	Insertion Pitch	Tape Thickness
	Α	В	F	Т
□MK105 (0402) □VK105 (0402)	0.65	1.15	2.0±0.05	0.8max.

Unit:mm



This catalog contains the typical specification only due to the limitation of space. When you consider the purchase of our products, please check our specification. For details of each product (characteristics graph, reliability information, precautions for use, and so on), see our Web site (http://www.ty-top.com/).

Type(EIA)	Chip (Cavity	Insertion Pitch	Tape Thickness
Type(EIA)	Α	В	F	Т
□MK107(0603)				
□WK107(0306) ※	1.0	1.8		1.1max.
☐MR107(0603)			40104	
□MK212(0805)	1.65	0.4	4.0±0.1	
□WK212(0508) ※	1.00	2.4		1.1max.
□MK316(1206)	2.0	3.6		

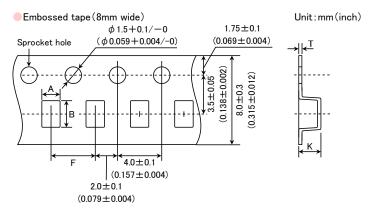
Note: Taping size might be different depending on the size of the product. 💥 LW Reverse type.

Unit:mm

Embossed tape (4mm wide)			Unit:mm(inch)
	ϕ 0.8 \pm 0.04	0.9 ± 0.05	
Sprocket hole	$(\phi 0.031 \pm 0.002)$	(0.035 ± 0.002)	_JL ^T
F 1.0±0.02 (0.039±0.001) (0	2.0±0.04 079±0.002)	(0.071±0.001) 4.0±0.05 (0.157±0.002)	K

Type(EIA)	Chip Cavity		Insertion Pitch	Tape Thickness		
Type(EIA)	Α	В	F	K	Т	
☐MK021(008004)	0.135	0.27				
☐MK042(01005)	0.23	0.42	1.0±0.02	0.5max.	0.25max.	
□VS042(01005)	0.23	0.43	0.43			

Unit:mm



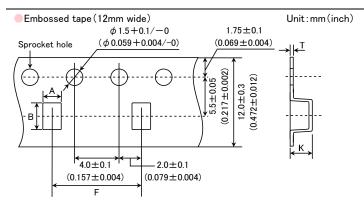
Type(EIA)	Chip (Chip Cavity		Tape Thickness	
Type(EIA)	Α	В	F	K	Т
☐MK105(0402)	0.6	1.1	2.0±0.1	0.6max	0.2±0.1
□WK107(0306) ※	1.0	1.8		1.3max.	0.25±0.1
□MK212(0805) □MR212(0805)	1.65	2.4	4.0±0.1		0.6max.
☐MK316(1206) ☐MR316(1206)	2.0	3.6		3.4max.	
☐MK325(1210) ☐MR325(1210)	2.8	3.6			

Note:

LW Reverse type.

Unit:mm

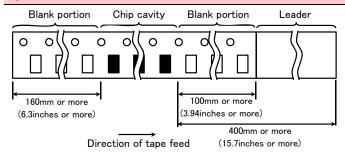
[►] This catalog contains the typical specification only due to the limitation of space. When you consider the purchase of our products, please check our specification. For details of each product (characteristics graph, reliability information, precautions for use, and so on), see our Web site (http://www.ty-top.com/).



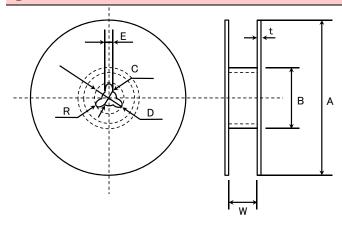
Turne/FIA)	Chip Cavity		Insertion Pitch	Tape Thickness	
Type(EIA)	Α	В	F	K	Т
☐MK325(1210)	3.1	4.0	8.0±0.1	4.0max.	0.6max.
☐MK432(1812)	3.7	4.9	8.0±0.1	4.0max.	0.6max.

Unit:mm

4 Trailer and Leader



5Reel size



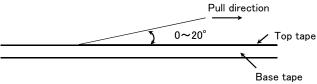
Α	В	С	D	E	R
ϕ 178 ± 2.0	<i>ф</i> 50min.	ϕ 13.0 \pm 0.2	ϕ 21.0 ± 0.8	2.0±0.5	1.0

	T	W
4mm wide tape	1.5max.	5±1.0
8mm wide tape	2.5max.	10±1.5
12mm wide tape	2.5max.	14±1.5

Unit:mm

©Top Tape Strength

The top tape requires a peel-off force of 0.1 to 0.7N in the direction of the arrow as illustrated below.



This catalog contains the typical specification only due to the limitation of space. When you consider the purchase of our products, please check our specification. For details of each product (characteristics graph, reliability information, precautions for use, and so on), see our Web site (http://www.ty-top.com/).

Multilayer Ceramic Capacitors

■ RELIABILITY DATA

Test

Methods and

Remarks

Applied voltage

Charge/discharge current

Duration

KELIABILIT	. 2						
1.Operating Te	mperature Range						
	Temperature	Standard					
	Compensating (Class1)	High Frequency Type	-55 to -	+125°C			
	Componicating (Class 1)	night Frequency Type	7				
				Specification	Temperature	Pange	
				B	-25 to +		
			BJ	X5R	-55 to +		
Specified			B7	X7R	-55 to +1		
Value	High Permittivity (Class2)	C6	X6S	-55 to +1		
	Trigit i Citilictivity (Olassz	,	C7	X7S	-55 to +1		
			D7	X7T	-55 to +1		
			LD(※)	X5R	-55 to +		
			<u> </u>	LD Low distortion I			
				.,	g		
	•		1				
2 Stawara Can	ditions						
2. Storage Cor	laitions	1	1				
	Temperature	Standard		+125°C			
	Compensating(Class1)	High Frequency Type	9				
				Specification	Temperature	Range	
			Б.	В	-25 to +	85°C	
Specified			BJ	X5R	-55 to +	85°C	
Value			B7	X7R	-55 to +1	25°C	
	High Permittivity (Class2)	C6	X6S	−55 to +1	05°C	
			C7	X7S	−55 to +1	25°C	
			D7	X7T	−55 to +1	25°C	
			LD(※)	X5R	-55 to +	85°C	
			Note: •	KLD Low distortion №	nigh value multilayer	ceramic capa	
3. Rated Volta	ge						
		Standard	50VDC 25	5VDC			
Specified	Temperature Compensating(Class1)			50VDC, 25VDC			
Value		High Frequency Type		50VDC, 25VDC			
	High Permittivity (Class2)	50VDC, 3	50VDC, 35VDC, 25VDC, 16VDC, 10VDC, 6.3VDC, 4VDC, 2.5VDC			
4. Withstanding	y Voltage (Between termina	ls)					
	Temperature	Standard					
Specified	Compensating (Class 1)		No break	lown or do			
Value		High Frequency Type	e No breakd	lown or damage			
	High Permittivity (Class2)					
T 4		(Class 1	(Class 2		
Test Methods and	Applied voltage	Rate	d volta × 3	Rated	voltage × 2.5		
Remarks	Duration			1 to 5 sec.			
Ciliains	Charge/discharge curren	nt		50mA max.			
			·				
5. Insulation Re	asistance						
J. Misulation Re		0					
	Temperature	Standard	10000 M S	2 min.			
Specified	Compensating(Class1)	High Frequency Type	9				
Value	High Demokratic to (OL C) N-+- 1	C≦0.047	μ F : 10000 MΩ min	l.		
	High Permittivity (Class2) Note I		<i>μ</i> F : 500M Ω • <i>μ</i> F			
T 4	A 1:1 1±	. D.4. J l4	_				

: Rated voltage

: 60±5 sec.

: 50mA max.

This catalog contains the typical specification only due to the limitation of space. When you consider the purchase of our products, please check our specification. For details of each product (characteristics graph, reliability information, precautions for use, and so on), see our Web site (http://www.ty-top.com/).

6. Capacitance	(Tolerance)					
Temperature (OL 1)	Standard	C□ U□ SL		: ±0.25pF : ±0.5pF : ±5% or ±10%		
Specified Value		High Frequency Type	СН	0.3pF≦C≦2pF C>2pF	: ±0.1pF : ±5%	
High Permittivity (Class2)		BJ, B7, C6, C7, D7, LD(※): = Note: ※LD Low distortion hig				c capacitor
			Class 1		CI	ass 2
- .		Standa	rd	High Frequency Type	C≦10 μ F	C>10 μ F
Test	Preconditioning		None		Thermal treatment (a	at 150°C for 1hr) Note 2
Remarks I —	Measuring frequency		1MH:	z±10%	1kHz±10%	120±10Hz
	Measuring voltage Note		0.5 to	5Vrms	1±0.2Vrms	0.5±0.1rms
Bias application					one	

Specified	Temperature Compensating(Class1)	Standard	ndard $C \le 30 \text{pF} : Q \ge 400 + 20 \text{C}$ $C \ge 30 \text{pF} : Q \ge 1000$ (C:Nominal capacitance)						
Value	Compensating (Glass I)	High Frequency Type		Refer	Refer to detailed specification				
	High Permittivity (Class2) Note 1			BJ, B7, C6, C7, D7:2.5% max.					
			Class 1		Class 2				
			Standard		High Frequency Type	C≦10 <i>μ</i> F	C>10 μ F		
	Preconditioning			None		Thermal treatment (at	150°C for 1hr) Note 2		
Test	Measuring frequey		1MHz±10%		1GHz	1kHz±10%	120±10Hz		
Methods and	Measuring voltage Note 1			0.5 to 5Vrms 1±0.2Vrms 0.5±0.1Vrms					
Remarks	Bias application			None					
	High Frequency Type								
	Measuring equipment	: HP	4291A						
	Measuring jig	: HP	16192A						

8. Temperature	e Characteristic (Without vo	ltage application)								
		Tem	perature Chara	cteristic [ppm/°	C] Tole	Tolerance [ppm/°C]				
Specified	Temperature Compensating(Class1)	Standard	C□:	0	CG,CH, CJ, (СК	G: ±30 H: ±60			
			U□: -750		UJ, UK		J:±120 K:±250			
			SL :	SL : +350 to -1000						
		High Frequency Type	Temperature Characteristic [ppm			C] Tole] Tolerance [ppm/°C]			
			C□:	C□: 0 CH H:±60						
			Specification	Capacitance	Reference	Tomporatura Panga				
Value				Specification	change	temperature	Temperature Range			
			BJ	В	±10%	20°C	−25 to +85°C			
			ВО	X5R	±15%	25°C	−55 to +85°C			
	High Downittivity (Class)	1	B7	X7R	±15%	25°C	−55 to +125°C			
	High Permittivity(Class2)		C6	X6S	±22%	25°C	−55 to +105°C			
			C7	X7S	±22%	25°C	−55 to +125°C			
			D7	X7S	+22/-33%	25°C	−55 to +125°C			
			LD(※)	X5R	±15%	25°C	-55 to +85°C			
			Note:	LD Low disto	ortion high value	multilayer ceran	nic capacitor			

Class 1

Capacitance at 20° C and 85° C shall be measured in thermal equilibrium, and the temperature characteristic shall be calculated from the following equation.

$$\frac{(C_{85}-C_{20})}{C_{20}\times\Delta T} \times 10^{6} (ppm/^{\circ}C) \qquad \Delta T = 65$$

Test Methods and Remarks

Class 2

Capacitance at each step shall be measured in thermal equilibrium, and the temperature characteristic shall be calculated from the following equation.

1 Minimum operating temperature 2 20°C 25°C	Step	В	X5R, X7R, X6S, X7S, X7T				
2 200	1	Minimum operat	ing temperature				
	2	20°C	25°C				
Maximum operating temperature	3	Maximum operating temperature					

This catalog contains the typical specification only due to the limitation of space. When you consider the purchase of our products, please check our specification. For details of each product (characteristics graph, reliability information, precautions for use, and so on), see our Web site (http://www.ty-top.com/).

 $\frac{(C-C_2)}{C_2}$ × 100(%)

C : Capacitance in Step 1 or Step 3

C2 : Capacitance in Step 2

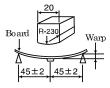
9. Deflection : No abnormality Appearance Standard Capacitance change : Within $\pm 5\%$ or ± 0.5 pF, whichever is larger. Temperature Compensating (Class 1)Appearance : No abnormality Specified High Frequency Type : Within±0.5 pF Cpaitance change Value Appearance : No abnormality Capacitance change : Within ±12.5%(BJ, B7, C6, C7, D7, LD(*)) High Permittivity (Class2)

Test Methods and

Remarks

	Multilayer Cera	mic Capacitors			
	042, 063, ^{※1} 105 Type	The other types			
Board	Glass epoxy-resin substrate				
Thickness	0.8mm	1.6mm			
Warp	1mm (Soft Termination type:3mm)				
Duration	10 sec.				





Note: XLD Low distortion high value multilayer ceramic capacitor

(Unit: mm)

Capacitance measurement shall be conducted with the board bent

10. Body Stren	10. Body Strength						
	Temperature	Standard					
Specified Value	Compensating(Class1)	High Frequency Type	No mechanical damage.				
Value	High Permittivity (Class2))	_				
Test Methods and Remarks	High Frequency Type Applied force : 5N Duration : 10 sec.	Pres ← A →	R0.5 Pressing Jig Chip A				

11. Adhesive St	trength of Terminal Electro	des				
	Temperature	Standard				
Specified Value	Compensating(Class1)	High Frequency Type	No terminal separati	on or its indication.		
	High Permittivity (Class2)					
	Multilayer Ceramic		Capacitors	Hooked jig		
Test		042, 063 Type	105 Type or more			
Methods and	Applied force	2N	5N	R=05 Doard		
Remarks	Duration	30±5 se	ec.			
				Chip		
- Temarks	3			Chip		

12. Solderability	12. Solderability								
	Temperature	Standard							
Specified Value	Compensating(Class1)	High Frequency Type At least 95% of terminal electrode is covered		of terminal electrode is covered	by new solder.				
Value	High Permittivity (Class2))							
T4		Eutectic so	older	Lead-free solder					
Test	Solder type	H60A or H	63A	Sn-3.0Ag-0.5Cu					
Methods and	Solder temperature	230±5°	С	245±3°C					
Remarks	Duration		4±1 sec.						

This catalog contains the typical specification only due to the limitation of space. When you consider the purchase of our products, please check our specification. For details of each product (characteristics graph, reliability information, precautions for use, and so on), see our Web site (http://www.ty-top.com/).

13. Resistance	to Soldering				
Specified Value	Temperature	Standard	Appearance Capacitance change Q Insulation resistance Withstanding voltage	: No abnormality : Within ±2.5% or ±0 : Initial value : Initial value (between terminals)	0.25pF, whichever is larger. : No abnormality
	Compensating(Class1)	High Frequency Type	Appearance Capacitancecange Q Insulation resistance Withstanding voltage	: No abnormality : Within ±2.5% : Initial value : Initial value (between terminals) : No abnormality	
	High Permittivity(Class	2) Note 1	Appearance : No abormality Capactace change : Within ±7.5%(BJ, E Dissipation factor : Initial value Insulation resistance : Initial value Withstanding voltage (between terminals) Note: ※LD Low distortion high value multilay		•
		lss 1			
		042, 063 Type	105 Type		
	Preconditioning		None		
	Preheating	150°C, 1 to 2 min.	80 to 100°C, 2 to 5 min. 150 to 200°C, 2 to 5 min.		
	Solder temp.		270±5°C		
	Duration		3 ± 0.5 sec.		
Γest Methods and	Recovery	6 to 24 hrs	s (Standard condition) N	loe 5	
Remarks				Class 2	
		042、063 Type	105, 1	07, 212 Type	316, 325 Type
	Preconditioning		Thermal treatment	(at 150°C for 1 hr) No	ote 2
	Preheating	150°C, 1 to 2 min.		00°C, 2 to 5 min. 00°C, 2 to 5 min.	80 to 100°C, 5 to 10 min. 150 to 200°C, 5 to 10 min.
	Solder temp.			.70±5°C	
	Duration		3:	±0.5 sec.	
	Recovery		24±2 hrs (Star	ndard condition)Note	5

14. Temperatur	re Cycle (Thermal Shock)						
Specified Value	Temperature	Standard		$ \begin{array}{lll} \mbox{Appearance} & : \mbox{No abnormality} \\ \mbox{Capacitance change} & : \mbox{Within $\pm 2.5\%$ or $\pm 0.25 pF$, whichever is larg} \\ \mbox{Q} & : \mbox{Initial value} \\ \mbox{Insulation resistance} & : \mbox{Initial value} \\ \mbox{Withstanding voltage} & (\mbox{between terminals}) : \mbox{No abnormality} \\ \end{array} $		-	
	Compensating(Class1)	High Frequency Type		Capacitance change : W Q : Ir Insulation resistance : Ir	: No abnormality : Within ±0.25pF : Initial value : Initial value (between terminals) : No abnormality		
	High Permittivity (Class2) Note 1			Appearance : No abnormality Capacitance change : Within ±7.5% (BJ, B7, C6, C7, D7, LD(※)) Dissipation factor : Initial value Insulation resistance : Initial value Withstanding voltage (between terminals) : No abnormality Note: ※LD Low distortion high value multilayer ceramic capacitor			
			C	lass 1		Class 2	
	Preconditioning			None	Thermal treatment (at 150°C for 1 hr) Note 2		
Test Methods and Remarks	1 cycle		Step 1 2 3 4	Temperature (°C) T Minimum operating temperature Normal temperature Maximum operating temperature Normal temperature		Time(min.) 30±3 2 to 3 30±3 2 to 3	
	Number of cycles			5 t	times		
	Recovery	6 to 24 hrs	(Stan	dard condition)Note 5	24±2 hrs(Standard condition)Note 5		

This catalog contains the typical specification only due to the limitation of space. When you consider the purchase of our products, please check our specification. For details of each product (characteristics graph, reliability information, precautions for use, and so on), see our Web site (http://www.ty-top.com/).

15. Humidity(Steady State)					
Specified Value	Temperature Compensating(Class1	Standard)	Appearance Capacitance change Q Insulation resistance	: No abnormality : Within $\pm 5\%$ or $\pm 0.5 pF$, whichever is larger. : $C < 10 pF : Q \ge 200 + 10 C$ $10 \le C < 30 pF : Q \ge 275 + 2.5 C$ $C \ge 30 pF : Q \ge 350 (C : Nominal capacitance)$: $1000 \ M\Omega$ min.		
		High Frequency Type	Appearance Capacitance change Insulation resistance	: No abnormality : Within $\pm 0.5 \text{pF}$, : 1000 M Ω min.		
	High Permittivity(Cla	uss2) Note 1		: No abnormality : Within \pm 12.5% (BJ, B7, C6, C7, D7, LD(\divideontimes)) : 5.0% max.(BJ, B7, C6, C7, D7, LD(\divideontimes)) : 50 M Ω μ F or 1000 M Ω whichever is smaller. on high value multilayer ceramic capacitor		
			ass 1	Class 2		
Test	Preconditioning	Standard N	High Frequency Type	All items Thermal treatment(at 150°C for 1 hr) Note 2		
Methods and	Temperature	40±2°C	60±2°C	40±2°C		
Remarks	Humidity	90 to	95%RH	90 to 95%RH		
	Duration	500+2	4/-0 hrs	500+24/-0 hrs		
	Recovery	6 to 24 hrs (Stand	ard condition)Note 5	24±2 hrs(Standard condition)Note 5		

16. Humidity Lo	pading					
Specified Value	Temperature	Appearance Capacitance change Q Insulation resistance		: No abnormality : Within $\pm 7.5\%$ or ± 0.75 pF, whichever is larger. : C $<$ 30pF: Q \ge 100+10C/3 C \ge 30pF: Q \ge 200 (C: Nominal capacitance) : 500 M Ω min.		
	Compensating(Class1)	High Frequency Type Capacitance change : C≦		No abnormality $C \leqq 2pF : \text{Within } \pm 0.4 \text{ pF}$ $C \gt 2pF : \text{Within } \pm 0.75 \text{ pF}$ $(C : \text{Nominal capacitance})$ 500 M\$\Omega\$ min.		
	High Permittivity (Class2) Note 1		$\begin{tabular}{lllllllllllllllllllllllllllllllllll$		thin ±12.5ν (BJ, B7, C6, C7, D7, LD(※)) % max. (BJ, B7, C6, C7, D7, LD(※)) ΜΩ μF or 500 ΜΩ, whichever is smaller.	
		C	Class 1		Class 2	
		Standard	High Frequency Type		All items	
	Preconditioning		None		Voltage treatment (Rated voltage are applied for 1 hour at 40°C) Note 3	
Test	Temperature	40±2°C	60±2°C		40±2°C	
Methods and	Humidity	90 t	o 95%RH		90 to 95%RH	
Remarks	Duration	500+	24/-0 hrs		500+24/-0 hrs	
	Applied voltage	Rate	d voltage		Rated voltage	
	Charge/discharge current	50r	mA max.		50mA max.	
	Recovery	6 to 24 hrs (Stan	dard condition)Note 5		24±2 hrs (Standard condition) Note 5	

This catalog contains the typical specification only due to the limitation of space. When you consider the purchase of our products, please check our specification. For details of each product (characteristics graph, reliability information, precautions for use, and so on), see our Web site (http://www.ty-top.com/).

17. High Tempe	erature Loading						
	Temperature Compensating(Class1)	Standard Appearance Capacitance change Q Insulation resistance		: C<10pF: Q≧200+10C 10≦C<30pF:Q≧275+2.5C C≧30pF: Q≧350(C:Nominal capacitance)			
Specified Value		High Frequency Type	High Frequency Type Appearance Capacitance change Insulation resistance				
	High Permittivity(Class2) Note 1	Appearance Capacitance change Dissipation factor Insulation resistance Note: **LD Low dis*	: 5.0% max.(BJ,	6(BJ, B7, C6, C7, D B7, C6, C7, D7, LD(1000 MΩ, whicheve	ێ)) r is smaller.	
		Clas	s 1	Class 2			
		Standard H	High Frequency Type	BJ, LD(<u>*</u>) C6 B7, C7, D7		B7, C7, D7	
	Preconditioning	Nor	ne	Voltage treatment (Twice the rated voltage shall be applied for 1 hour at 85°C, 105°C or 125°C) Note 3, 4			
Test	Temperature	Maximum operatii	ng temperature	Maximum operating temperature			
Methods and	Duration	1000+48	/-0 hrs		1000+48/-0 hr	'S	
Remarks	Applied voltage	Rated vol	tage × 2	Rated voltage × 2 Note 4			
Remarks	Charge/discharge current	50mA	max.	50mA max.			
	Recovery	6 to 24hr(Standard	condition) Note 5	24±2 hrs(Standard condition)Note 5			
			Note:	: XLD Low distortion high value multilayer ceramic capacitor			

Note 1 The figures indicate typical specifications. Please refer to individual specifications in detail.

- Note 2 Thermal treatment : Initial value shall be measured after test sample is heat-treated at $150 + 0/-10^{\circ}$ C for an hour and kept at room temperature for 24 ± 2 hours.
- Note 3 Voltage treatment: Initial value shall be measured after test sample is voltage—treated for an hour at both the temperature and voltage specified in the test conditions, and kept at room temperature for 24±2hours.
- Note 4 150% of rated voltage is applicable to some items. Please refer to their specifications for further information.
- Note 5 Standard condition: Temperature: 5 to 35°C, Relative humidity: 45 to 85 % RH, Air pressure: 86 to 106kPa When there are questions concerning measurement results, in order to provide correlation data, the test shall be conducted under the following condition.
 - Temperature: 20±2°C, Relative humidity: 60 to 70 % RH, Air pressure: 86 to 106kPa Unless otherwise specified, all the tests are conducted under the "standard condition".

[►] This catalog contains the typical specification only due to the limitation of space. When you consider the purchase of our products, please check our specification. For details of each product (characteristics graph, reliability information, precautions for use, and so on), see our Web site (http://www.ty-top.com/).

Medium-High Voltage Multilayer Ceramic Capacitor

100VDC(HMK,HMJ), 250VDC(QMK,QMJ,QVS), 630VDC(SMK,SMJ)

: 50mA max.

■ RELIABILITY DATA

	Temperature Compensating(High Frequency type) CG(C0G) : -55 to +125°C
Specified Value	High permittivity
	X7R, X7S : −55 to +125°C
	X5 : -55 to +85°C
	B : -25 to +85°C
2. Storage Tempe	Temperature Compensating(High Frequency type) CG(C0G) : -55 to +125°C
Specified Value	High permittivity
Specified Value	High permittivity X7R, X7S : −55 to +125°C
Specified Value	

Carge/discharge current

4. Withstanding Volt	tage (Between terminals)	
Specified Value	No breakdown or damage	
Test Methods and Remarks	Applied voltage Duration	: Rated voltage × 2.5 (HMK,HMJ), Rated voltage × 2 (QMK,QMJ,QVS), Rated voltage × 1.2 (SMK,SMJ) : 1 to 5 sec.

5. Insulation Resistance

3. Rated Voltage
Specified Value

Specified Value	Temperature Compensating 10000M Ω min	(High Frequency type)
•	High permittivity 100M Ω μ F or 10G Ω , which	never is smaller.
Test Methods and Remarks	Applied voltage Duration Charge/discharge current	: Rated voltage(HMK,HMJ, QMK,QMJ,QVS), 500V(SMK,SMJ) : 60±5sec. : 50mA max.

6. Capacitance (Tolerance)
------------------	------------

Specified Value	Temperature Compensating ±0.1pF (C<5pF) ±0.25pl High permittivity ±10%, ±20%	g(High Frequency type) F(C<10pF) ±0.5pF(5pF≦C<10pF) ±2%(C=10pF) ±5%(C≧10pF)
Test Methods and Remarks	Temperature Compensating Measuring frequency Measuring voltage Bias application High permittivity Measuring frequency Measuring voltage Bias application	g(High Frequency type) : 1MHz±10% : 0.5 to 5Vrms : None : 1kHz±10% : 1±0.2Vrms : None

This catalog contains the typical specification only due to the limitation of space. When you consider the purchase of our products, please check our specification. For details of each product (characteristics graph, reliability information, precautions for use, and so on), see our Web site (http://www.ty-top.com/).

7. Q or Dissipation	Factor		
	Temperature Compensa	ting(High Frequency type)	
	C<30pF: Q≧800+20		
	C≧30pF: Q≧1400	C:Normal Capacitance(/pF)	
Specified Value			
	High permittivity		
	3.5%max(HMK,HMJ)		
	2.5%max(QMK,QMJ, SM	K,SMJ)	
	Temperature Compensa	ting(High Frequency type)	
	Measuring frequency	: 1MHz±10%	
	Measuring voltage	: 0.5 to 5Vrms	
Test Methods and	Bas application	: None	
Remarks	High permittivity		
	Measuring frequency	: 1kHz±10%	
	Measuring voltage	: 1±0.2Vrms	
	Bas application	: None	

8. Temperature Ch	aracteristic of Capacitance
	Temperature Compensating(High Frequency type) COG :±30ppm(25 to +125°C)
Specified Value	High permittivity B : ±10%(-25 to +85°C) X5R : ±15%(-55 to +85°C) X7R : ±15%(-55 to +125°C) X7S : ±22%(-55 to +125°C)
Test Methods and Remarks	Temperature Compensating(High Frequency type) Capacitance at 25°C and 85°C shall be measured in thermal equilibrium, and the temperature characteristic shall be calculated from the following equation. $\frac{(C_{65}-C_{25})}{C_{25}\times\Delta T}\times 10^6\times [\text{ppm/°C}]$ High permittivity Capacitance value at each step shall be measured in thermal equilibrium, and the temperature characteristic shall be calculated from the following equation. $\frac{\text{Step}}{1} \frac{\text{B}}{\text{Minimum operating tempeature}} \times \frac{\text{X5R} \times \text{X7R} \times \text{X7S}}{1} \times \frac{\text{Minimum operating tempeature}}{1} \times \frac{\text{CC-C}_2}{2} \times 100\%$ $\frac{(\text{C-C}_2)}{C_2} \times 100\%$ C : Capacitance value in Step 1 or Step 3 C2 : Capacitance value in Step 2

	Temperature Compensating(High Frequency type)
	Appearance : No abnormality
	Capacitance change :±5% or ±0.5pF, whichever is larger.
Specified Value	
	High permittivity
	Appearance : No abnormality Capacitance change : Within±10%
Test Methods and Remarks	Warp : 1mm (Soft Termination type:3mm) Duration : 10sec. Test board : Glass epoxy-resin substrate Thicknss : 1.6mm Board R-230 Warp
	(Unit: mm)
	Capacitance measurement shall be conducted with the board bent.

This catalog contains the typical specification only due to the limitation of space. When you consider the purchase of our products, please check our specification. For details of each product (characteristics graph, reliability information, precautions for use, and so on), see our Web site (http://www.ty-top.com/).

10. Adhesive Strength of Terminal Electrodes Specified Value No terminal separation or its indication. Temperature Compensating(High Frequency type) Applied force : 2N Hooked jig Duration : 10±5sec. Test Methods and Remarks High permittivity Applied force : 5N Hooked jig Duration : 30±5sec. Board

11. Solderability			
Specified Value	At least 95% of terminal elect	trode is covered by new solder	
		Eutectic solder	Lead-free solder
Test Methods and	Solder type	H60A or H63A	Sn-3.0Ag-0.5Cu
Remarks	Solder temperature	230±5°C	245±3°C
	Duration	4±1	sec.

12. Resistance to S	Soldering					
	Temperature Compensating(High Frequency type)					
	Appearance	: No abnormality				
	Capacitance change	: C※≦10pF :±0.25pF C※>10pF :±2.5% ※Normal capacitance				
	Insulation resistance	: Initial value				
	Withstanding voltage	(between terminals): No abnormality				
Specified Value	High permittivity					
	Appearance	: No abnormality				
	Capacitance change	: Within±15%(HMK,HMJ), ±10%(QMK,QMJ, SMK,SMJ)				
	Dissipation factor	: Inital value				
	Insulation resistance	: Initial value				
	Withstanding voltage	(between terminals): No abnormality				
	Preconditioning	: Thermal treatment(at 150°C for 1hr) Note1 (Only High permittivity)				
Test Methods and	Solder temperature	: 270±5℃				
Remarks	Duration	: 3±0.5sec.				
remarks	Preheating conditions	: 80 to 100°C, 2 to 5 min. 150 to 200°C, 2 to 5min.				
	Recovery	: 24±2hrs under the stadard condition Note3				

	•				
13. Temperature Cy	ycle (Thern	nal Shock)			
	Temperature Compensating(High Frequency type)				
	Appearance	ce	: No abnormality		
	Capacitan	ce change	: C‰≦10pF :±0.25% C‰>10pF :±2.5%		
	Insulation	resistance	: Initial value		
	Withstand	ing voltage	(between terminals): No abnormality		
Specified Value	High perm	ittivity			
	Appearance		: No abnormality		
	Capacitance change		: Within±15%(HMK,HMJ), ±7.5%(QMK,QMJ, SMK,SMJ)		
	Dissipation factor : Initial		: Initial value		
	Insulation resistance : Initial value				
	Withstand	ing voltage	voltage (between terminals): No abnormality		
	Preconditi	ioning : Thern	nal treatment (at 150°C for 1hr) Note1		
	Conditions	s for 1 cycle			_
	Step		temperature (°C)	Time (min.)	
Test Methods and	1		Minimum operating temperature	30±3min.	
Remarks	2		Normal temperature	2 to 3min.	
Remarks	3		Maximum operating temperature	30±3min.	
	4	Normal temperature		2 to 3min.]
	Number of	f cycles : 5 ti	mes		
	Recovery	: 24±2hrs u	nder the standard condition Note3		

This catalog contains the typical specification only due to the limitation of space. When you consider the purchase of our products, please check our specification. For details of each product (characteristics graph, reliability information, precautions for use, and so on), see our Web site (http://www.ty-top.com/).

	dy state)	
	Temperature Compensating(
	Appearance	: No abnormality
	Capacitance change	: C※≦10pF :±0.5pF C※>10pF :±5%
	Insulation resistance	: $1000M\Omega$ min
Specified Value	Ulada manusitativita	
	High permittivity Appearance	: No abnormality
	Capacitance change	: Within±15%
	Dissipation factor	: 78max(HMK.HMJ). 58max(QMK.QMJ. SMK.SMJ).
	Insulation resistance	: 25MΩ $μ$ F or $1000MΩ$, whichever is smaller.
	Preconditioning	: Thermal treatment (at 150°C for 1hr) Note1 (Only High permittivity)
	Temperature	: 40±2°C
Test Methods and	Humidity	: 90 to 95%RH
Remarks	Duration	500 + 24/-0 hrs
	Recovery	: 24±2hrs under the standard condition Note3
15. Humidity Loading	g	
	Temperature Compensating((High Frequency type)
	Appearance	: No abnormality
	Capacitance change	: C※≦2.0pF:±0.4pF 2.0pF <c≦10pf: c※="" ±0.75pf="">10pF:±7.5%</c≦10pf:>
		: **Normal capacitance
	Insulation resistance	: $500M\Omega$ min
Specified Value	10.1	
	High permittivity	Maraharama Ph.
	Appearance	: No abnormality : Within±15%
	Capacitance change Dissipation factor	: Within ± 15% : 7%max(HMK,HMJ), 5%max(QMK,QMJ, SMK,SMJ).
	Insulation resistance	: 10M Ω μ F or 500M Ω , whichever is smaller.
	According to JIS 5102 claus	
	Preconditioning	: Voltage treatment Note2 (Only High permittivity)
Taak Makka da aa d	Temperature	: 40±2°C
Test Methods and Remarks	Humidity	: 90 to 95%RH : Rated voltage
temarks	Applied voltage Charge/discharge current	: 50mA max.
	Duration	: 500 +24/-0 hrs
	Recovery	: 24±2hrs under the standard condition Note3
	Hoody	. El Ellio diladi dio standa di sondissi riotto
16. High Temperatur	re Loading	
	Temperature Compensating((High Frequency type)
	Appearance	: No abnormality
	Capacitance change	: C※≦10pF :±0.3pF C※>10pF :±3%
	Insulation resistance	:1000M Ω min
Specified Value	18.1	
	High permittivity	M. J. Ps
	Appearance	: No abnormality
	Capacitance change	: Within±15%
	Dissipation factor Insulation resistance	: 7%max(HMK,HMJ), 5%max(QMK,QMJ, SMK,SMJ). : 50M Ω μ F or 1000M Ω , whichever is smaller.
	According to JIS 5102 claus Preconditioning	e 9.10. : Voltage treatment Note2 (Only High permittivity)
	Temperature	: Maximum operating temperature
	Applied voltage	: Rated voltage × 2 (HMK,HMJ,QVS) Rated voltage × 1.5 (QMK,QMJ) Rated voltage × 1.2 (SMK,SMJ)
Test Methods and	PPIIOG FOICGBO	: 50mA max.
Test Methods and Remarks	Charge/discharge current	
	Charge/discharge current Duration	
	Charge/discharge current Duration Recovery	: $1000 + 24/-0$ hrs : 24 ± 2 hrs under the standard condition Note3

the test conditions, and kept at room temperature for $24\pm2\text{hours}$.

Note3 Standard condition : Temperature: 5 to 35°C, Relative humidity: 45 to 85 % RH, Air pressure: 86 to 106kPa

When there are questions concerning measurement results, in order to provide correlation data, the test shall be conducted

under the following condition.

Temperature: 20±2°C, Relative humidity: 60 to 70 % RH, Air pressure: 86 to 106kPa Unless otherwise specified, all the tests are conducted under the "standard condition".

Finis catalog contains the typical specification only due to the limitation of space. When you consider the purchase of our products, please check our specification. For details of each product (characteristics graph, reliability information, precautions for use, and so on), see our Web site (http://www.ty-top.com/) .

Precautions on the use of Multilayer Ceramic Capacitors

■PRECAUTIONS

1. Circuit Design

- ◆Verification of operating environment, electrical rating and performance
 - 1. A malfunction of equipment in fields such as medical, aerospace, nuclear control, etc. may cause serious harm to human life or have severe social ramifications.

Therefore, any capacitors to be used in such equipment may require higher safety and reliability, and shall be clearly differentiated from them used in general purpose applications.

Precautions

- ◆Operating Voltage (Verification of Rated voltage)
 - 1. The operating voltage for capacitors must always be their rated voltage or less.
 - If an AC voltage is loaded on a DC voltage, the sum of the two peak voltages shall be the rated voltage or less.
 - For a circuit where an AC or a pulse voltage may be used, the sum of their peak voltages shall also be the rated voltage or less.
 - 2. Even if an applied voltage is the rated voltage or less reliability of capacitors may be deteriorated in case that either a high frequency AC voltage or a pulse voltage having rapid rise time is used in a circuit.

2. PCB Design

Precautions

- ◆Pattern configurations (Design of Land-patterns)
- 1. When capacitors are mounted on PCBs, the amount of solder used (size of fillet) can directly affect the capacitor performance. Therefore, the following items must be carefully considered in the design of land patterns:
 - (1) Excessive solder applied can cause mechanical stresses which lead to chip breaking or cracking. Therefore, please consider appropriate land-patterns for proper amount of solder.
 - (2) When more than one component are jointly soldered onto the same land, each component's soldering point shall be separated by solder-resist.
- ◆Pattern configurations (Capacitor layout on PCBs)

After capacitors are mounted on boards, they can be subjected to mechanical stresses in subsequent manufacturing processes (PCB cutting, board inspection, mounting of additional parts, assembly into the chassis, wave soldering of the boards, etc.). For this reason, land pattern configurations and positions of capacitors shall be carefully considered to minimize stresses.

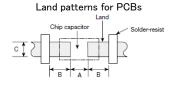
◆Pattern configurations (Design of Land-patterns)

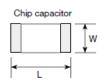
The following diagrams and tables show some examples of recommended land patterns to prevent excessive solder amounts.

- (1) Recommended land dimensions for typical chip capacitors
- Multilayer Ceramic Capacitors : Recommended land dimensions (unit: mm)

Wave-soldering

Туре		107	212	316	325
Size	L	1.6	2.0	3.2	3.2
Size	W	0.8	1.25	1.6	2.5
P	4	0.8 to 1.0	1.0 to 1.4	1.8 to 2.5	1.8 to 2.5
Е	3	0.5 to 0.8	0.8 to 1.5	0.8 to 1.7	0.8 to 1.7
С		0.6 to 0.8	0.9 to 1.2	1.2 to 1.6	1.8 to 2.5
		0.0 to 0.0	0.0 to 1.2	1.2 00 1.0	1.0 to 2.0





Reflow-soldering

Technical considerations

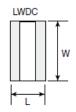
		0							
Ту	ре	042	063	105	107	212	316	325	432
Size	L	0.4	0.6	1.0	1.6	2.0	3.2	3.2	4.5
SIZE	W	0.2	0.3	0.5	0.8	1.25	1.6	2.5	3.2
A	١	0.15 to 0.25	0.20 to 0.30	0.45 to 0.55	0.8 to 1.0	0.8 to 1.2	1.8 to 2.5	1.8 to 2.5	2.5 to 3.5
Е	3	0.15 to 0.20	0.20 to 0.30	0.40 to 0.50	0.6 to 0.8	0.8 to 1.2	1.0 to 1.5	1.0 to 1.5	1.5 to 1.8
C	;	0.15 to 0.30	0.25 to 0.40	0.45 to 0.55	0.6 to 0.8	0.9 to 1.6	1.2 to 2.0	1.8 to 3.2	2.3 to 3.5

Note: Recommended land size might be different according to the allowance of the size of the product.

●LWDC: Recommended land dimensions for reflow-soldering

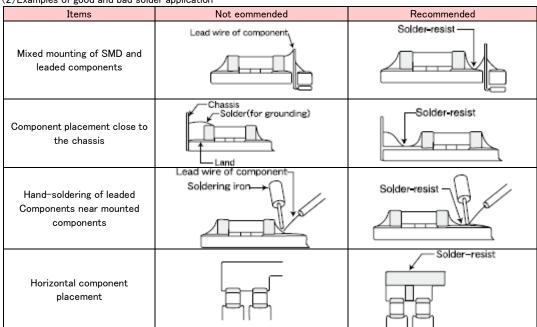
(unit: mm)

(=====================================					
Type		105 107		212	
Size	┙	0.52	0.8	1.25	
Size	W	1.0	1.6	2.0	
Α		0.18 to 0.22	0.25 to 0.3	0.5 to 0.7	
В		0.2 to 0.25		0.4 to 0.5	
С		0.9 to 1.1	1.5 to 1.7	1.9 to 2.1	



This catalog contains the typical specification only due to the limitation of space. When you consider the purchase of our products, please check our specification. For details of each product (characteristics graph, reliability information, precautions for use, and so on), see our Web site (http://www.ty-top.com/).

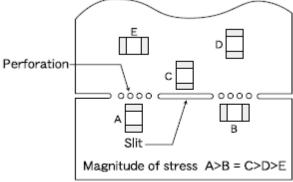
(2) Examples of good and bad solder application



- ◆Pattern configurations (Capacitor layout on PCBs)
 - 1-1. The following is examples of good and bad capacitor layouts; capacitors shall be located to minimize any possible mechanical stresses from board warp or deflection.

Items	Not recommended	Recomm	mended
Deflection of board			Place the product at a right angle to the direction of the anticipated mechanical stress.

1-2. The amount of mechanical stresses given will vary depending on capacitor layout. Please refer to diagram below.



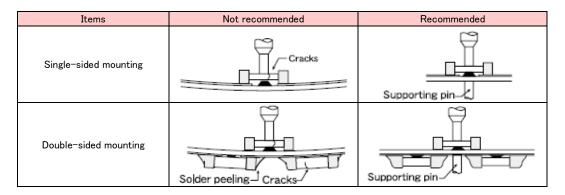
1-3. When PCB is split, the amount of mechanical stress on the capacitors can vary according to the method used. The following methods are listed in order from least stressful to most stressful: push-back, slit, V-grooving, and perforation. Thus, please consider the PCB, split methods as well as chip location.

Adjustment of mounting machine 1. When capacitors are mounted on PCB, excessive impact load shall not be imposed on them. 2. Maintenance and inspection of mounting machines shall be conducted periodically. ◆ Selection of Adhesives 1. When chips are attached on PCBs with adhesives prior to soldering, it may cause capacitor characteristics degradation unless the following factors are appropriately checked: size of land patterns, type of adhesive, amount applied, hardening temperature and hardening period. Therefore, please contact us for further information. ◆ Adjustment of mounting machine 1. When the bottom dead center of a pick-up nozzle is too low, excessive force is imposed on capacitors and causes damages. To avoid this, the following points shall be considerable. (1) The bottom dead center of the pick-up nozzle shall be adjusted to the surface level of PCB without the board deflection.

- considerations
- (1) The bottom dead center of the pick-up nozzle shall be adjusted to the surface level of PCB without the board deflection.

 (2) The pressure of nozzle shall be adjusted between 1 and 3 N static loads.
- (3) To reduce the amount of deflection of the board caused by impact of the pick-up nozzle, supporting pins or back-up pins shall be used on the other side of the PCB. The following diagrams show some typical examples of good and bad pick-up nozzle placement:

This catalog contains the typical specification only due to the limitation of space. When you consider the purchase of our products, please check our specification. For details of each product (characteristics graph, reliability information, precautions for use, and so on), see our Web site (http://www.ty-top.com/).



2. As the alignment pin is worn out, adjustment of the nozzle height can cause chipping or cracking of capacitors because of mechanical impact on the capacitors.

To avoid this, the monitoring of the width between the alignment pins in the stopped position, maintenance, check and replacement of the pin shall be conducted periodically.

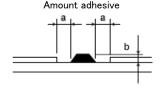
Selection of Adhesives

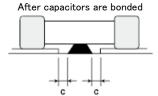
Some adhesives may cause IR deterioration. The different shrinkage percentage of between the adhesive and the capacitors may result in stresses on the capacitors and lead to cracking. Moreover, too little or too much adhesive applied to the board may adversely affect components. Therefore, the following precautions shall be noted in the application of adhesives.

- (1) Required adhesive characteristics
 - a. The adhesive shall be strong enough to hold parts on the board during the mounting & solder process.
 - b. The adhesive shall have sufficient strength at high temperatures.
 - c. The adhesive shall have good coating and thickness consistency.
 - d. The adhesive shall be used during its prescribed shelf life.
 - e. The adhesive shall harden rapidly.
 - f. The adhesive shall have corrosion resistance.
 - g. The adhesive shall have excellent insulation characteristics.
 - h. The adhesive shall have no emission of toxic gasses and no effect on the human body.
- (2) The recommended amount of adhesives is as follows;

[Recommended condition]

Figure	212/316 case sizes as examples
а	0.3mm min
b	100 to 120 μ m
С	Adhesives shall not contact land





4. Soldering

Precautions

◆Selection of Flux

Since flux may have a significant effect on the performance of capacitors, it is necessary to verify the following conditions prior to use;

- (1) Flux used shall be less than or equal to 0.1 wt% (in Cl equivalent) of halogenated content. Flux having a strong acidity content shall not be applied.
- (2) When shall capacitors are soldered on boards, the amount of flux applied shall be controlled at the optimum level.
- (3) When water-soluble flux is used, special care shall be taken to properly clean the boards.

◆ Soldering

Temperature, time, amount of solder, etc. shall be set in accordance with their recommended conditions.

Sn-Zn solder paste can adversely affect MLCC reliability.

Please contact us prior to usage of Sn-Zn solder.

◆Selection of Flux

- 1-1. When too much halogenated substance (Chlorine, etc.) content is used to activate flux, or highly acidic flux is used, it may lead to corrosion of terminal electrodes or degradation of insulation resistance on the surfaces of the capacitors.
- 1-2. Flux is used to increase solderability in wave soldering. However if too much flux is applied, a large amount of flux gas may be emitted and may adversely affect the solderability. To minimize the amount of flux applied, it is recommended to use a flux-bubbling system.
- 1-3. Since the residue of water-soluble flux is easily dissolved in moisture in the air, the residues on the surfaces of capacitors in high humidity conditions may cause a degradation of insulation resistance and reliability of the capacitors. Therefore, the cleaning methods and the capability of the machines used shall also be considered carefully when water-soluble flux is used.

Technical considerations

♦Soldering

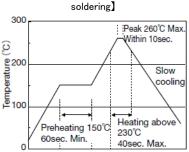
- · Ceramic chip capacitors are susceptible to thermal shock when exposed to rapid or concentrated heating or rapid cooling.
- · Therefore, the soldering must be conducted with great care so as to prevent malfunction of the components due to excessive thermal
- Preheating: Capacitors shall be preheated sufficiently, and the temperature difference between the capacitors and solder shall be within 100 to 130°C.
- Cooling: The temperature difference between the capacitors and cleaning process shall not be greater than 100°C.
- This catalog contains the typical specification only due to the limitation of space. When you consider the purchase of our products, please check our specification. For details of each product (characteristics graph, reliability information, precautions for use, and so on), see our Web site (http://www.ty-top.com/).

[Reflow soldering]

[Recommended conditions for eutectic

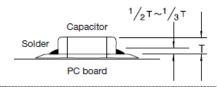
soldering Preheating 230°C Within 10 sec. 60sec 60sec Temperature (°C) 200 Min. Slow cooling 100

Recommended condition for Pb-free



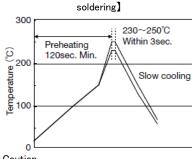
Caution

- \bigcirc The ideal condition is to have solder mass(fillet) controlled to 1/2 to 1/3 of the thickness of a capacitor.
- ②Because excessive dwell times can adversely affect solderability, soldering duration shall be kept as close to recommended times as possible.
- 3 Allowable number of reflow soldering: 2 times max.

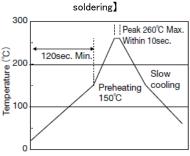


[Wave soldering]

[Recommended conditions for eutectic



[Recommended condition for Pb-free

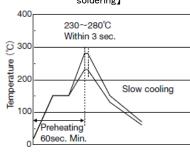


Caution

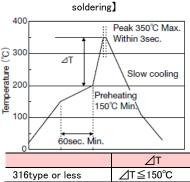
- ①Wave soldering must not be applied to capacitors designated as for reflow soldering only.
- 2 Allowable number of wave soldering: 1 times max.

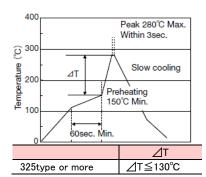
[Hand soldering]

[Recommended conditions for eutectic soldering]



[Recommended condition for Pb-free





- ①Use a 50W soldering iron with a maximum tip diameter of 1.0 mm.
- 2The soldering iron shall not directly touch capacitors.
- 3 Allowable number of hand soldering: 1 times max.

5. Cleaning

Precautions

- ◆Cleaning conditions
 - 1. When PCBs are cleaned after capacitors mounting, please select the appropriate cleaning solution in accordance with the intended use of the cleaning. (e.g. to remove soldering flux or other materials from the production process.)
 - 2. Cleaning condition shall be determined after it is verified by using actual cleaning machine that the cleaning process does not affect capacitor's characteristics.

Technical considerations

- 1. The use of inappropriate cleaning solutions can cause foreign substances such as flux residue to adhere to capacitors or deteriorate their outer coating, resulting in a degradation of the capacitor's electrical properties (especially insulation resistance).
- 2. Inappropriate cleaning conditions (insufficient or excessive cleaning) may adversely affect the performance of In the case of ultrasonic cleaning, too much power output can cause excessive vibration of PCBs which may lead cracking of capacitors or the soldered portion, or decrease the terminal electrodes' strength. Therefore, the following conditions shall be carefully checked;

Ultrasonic output: 20~W/l or less Ultrasonic frequency: 40 kHz or less

This catalog contains the typical specification only due to the limitation of space. When you consider the purchase of our products, please check our specification. For details of each product (characteristics graph, reliability information, precautions for use, and so on), see our Web site (http://www.ty-top.com/)

	Ultrasonic washing period : 5 min. or less
6. Resin coating	and mold
Precautions	 With some type of resins, decomposition gas or chemical reaction vapor may remain inside the resin during the hardening period of while left under normal storage conditions resulting in the deterioration of the capacitor's performance. When a resin's hardening temperature is higher than capacitor's operating temperature, the stresses generated by the excessive hear
	may lead to damage or destruction of capacitors. The use of such resins, molding materials etc. is not recommended.

7. Handling	
	◆Splitting of PCB 1. When PCBs are split after components mounting, care shall be taken so as not to give any stresses of deflection or twisting to the board. 2. Board separation shall not be done manually, but by using the appropriate devices.
Precautions	 ◆Mechanical considerations Be careful not to subject capacitors to excessive mechanical shocks. (1) If ceramic capacitors are dropped onto a floor or a hard surface, they shall not be used. (2) Please be careful that the mounted components do not come in contact with or bump against other boards or components.

8. Storage condi	tions
Precautions	 ◆Storage 1. To maintain the solderability of terminal electrodes and to keep packaging materials in good condition, care must be taken to control temperature and humidity in the storage area. Humidity should especially be kept as low as possible. •Recommended conditions Ambient temperature: Below 30°C Humidity: Below 70% RH The ambient temperature must be kept below 40°C. Even under ideal storage conditions, solderability of capacitor is deteriorated as time passes, so capacitors shall be used within 6 months from the time of delivery. •Ceramic chip capacitors shall be kept where no chlorine or sulfur exists in the air. The capacitance values of high dielectric constant capacitors will gradually decrease with the passage of time, so care shall be taken to design circuits. Even if capacitance value decreases as time passes, it will get back to the initial value by a heat treatment at 150°C for 1hour.
Technical considerations	If capacitors are stored in a high temperature and humidity environment, it might rapidly cause poor solderability due to terminal oxidation and quality loss of taping/packaging materials. For this reason, capacitors shall be used within 6 months from the time of delivery. If exceeding the above period, please check solderability before using the capacitors.

**RCR-2335B (Safety Application Guide for fixed ceramic capacitors for use in electronic equipment) is published by JEITA. Please check the guide regarding precautions for deflection test, soldering by spot heat, and so on.

[▶] This catalog contains the typical specification only due to the limitation of space. When you consider the purchase of our products, please check our specification. For details of each product (characteristics graph, reliability information, precautions for use, and so on), see our Web site (http://www.ty-top.com/).

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

Taiyo Yuden:

```
TMK316ABJ106KD-T TMK107ABJ225KA-T TMK212AB7475KG-T TMK212AB7475MG-T TMK212BBJ106KG-T
TMK212BBJ475KD-T TMK316AB7475KL-T UMK212ABJ105KD-T UMK316AB7475KL-T UMK316ABJ475KD-T
UMK325AB7106KM-T EMK107ABJ475KA-T EMK212ABJ106KD-T EMK212ABJ225KD-T EMK325ABJ107MM-T
GMK325AB7106MM-T JMK105BBJ475MV-F JMK212AB7106KG-T UMK325AB7106MM-T UMK107ABJ474KA-T
UMK212BB7225KG-T AMK105CBJ106MV-F EMK107BBJ106MA-T EMK212BBJ226MG-T TMK316BBJ226ML-T
UMK107AB7105KA-T UMK316BBJ106ML-T EMK316ABJ226ML-T JMK212BBJ476MG-T AMK107ABJ106MAHT
AMK107BBJ226MAHT AMK212ABJ226MGHT AMK212AC6226MG-T AMK212BBJ476MGHT AMK212BC6476MG-T
 AMK316AB7226MLHT AMK316ABJ107MLHT AMK325ABJ107MMHT AMK325ABJ227MM-T EMK105ABJ225MV-F
 EMK105ABJ474KV-F EMK107ABJ225KAHT EMK107B7105KAHT EMK107B7473KAHT EMK107B7474KAHT
EMK107BJ104KAHT EMK107BJ105KAHT EMK107BJ224KAHT EMK107BJ474KAHT EMK212AB7475KGHT
EMK212ABJ225KDHT EMK212ABJ475KGHT EMK212B7105KGHT EMK212B7224KGHT EMK212B7225KGHT
EMK212B7474KGHT EMK212BB7106MG-T EMK212BBJ106KGHT EMK212BJ105KDHT EMK212BJ105KGHT
EMK212BJ225KGHT EMK212BJ475KDHT EMK316AB7106KLHT EMK316AB7106KL-T EMK316AB7475KLHT
EMK316B7225KLHT EMK316BBJ226MLHT EMK316BJ106KLHT EMK316BJ225KLHT EMK316BJ475KLHT
EMK325B7106KNHT EMK325B7226KMHT EMK325B7226MMHT EMK325BJ106MNHT EMK325BJ226MMHT
EMK325BJ475MNHT GMK107AB7105KAHT GMK107ABJ474KAHT GMK107B7104KAHT GMK107B7224KAHT
GMK107B7474KAHT GMK107BJ104KAHT GMK107BJ105KAHT GMK107BJ223KAHT GMK107BJ224KAHT
GMK107BJ473KAHT GMK212B7105KGHT GMK212B7224KGHT GMK212BJ104KGHT GMK212BJ105KGHT
GMK212BJ224KGHT GMK212BJ474KGHT GMK316AB7475KLHT GMK316B7105KLHT GMK316B7225KLHT
GMK316BJ105KLHT GMK316BJ225KLHT GMK316BJ475KLHT GMK325B7225MNHT GMK325BJ106MMHT
```